



#### **DUAL P-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

BV <sub>DSS</sub>	$R_{DS(ON)}$ max $I_D$ max $T_A = +25$			
001/	0.9Ω @ V <sub>GS</sub> = -10V	-0.55A		
-30V	1.7Ω @ V <sub>GS</sub> = -4.5V	-0.4A		

## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- **Power Management Functions**
- **DC-DC Converters**

# **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Mechanical Data**

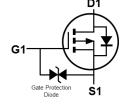
- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.027 grams (Approximate)



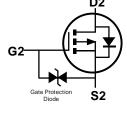




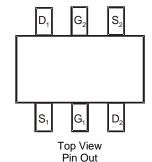
Top View



Q1 P-Channel



Q2 P-Channel



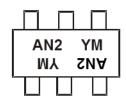
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP31D7LDW-7	SOT363	3,000/Tape & Reel
DMP31D7LDW-13	SOT363	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



AN2= Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  or  $\underline{Y}$ = Year (ex: G = 2019) M = Month (ex: 9 = September)

Date Code Key

Year	2019	2	020	2021		2022	2023		2024	2025		2026
Code	G		Н	!		J	K		L	M		N
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-30	V
Gate-Source Voltage	$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Ι <sub>D</sub>	-0.55 -0.44	А
Maximum Continuous Body Diode Forward Current (Note 6)	Is	-0.38	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	-2.4	Α

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		$P_{D}$	0.29	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>OJA</sub>	433	°C/W	
Total Power Dissipation (Note 6)		$P_{D}$	0.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>OJA</sub>	301	°C/W
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C	

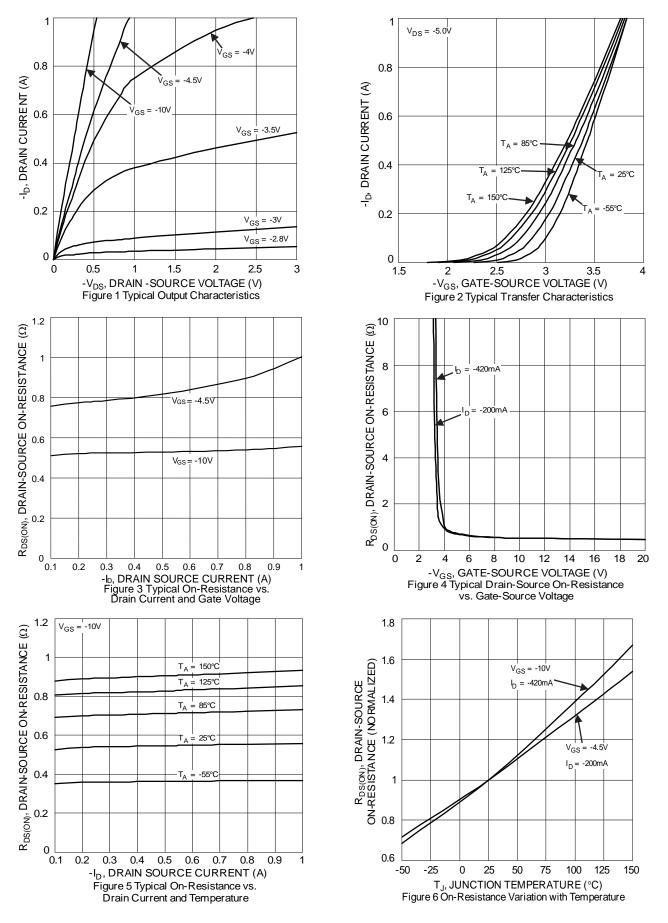
# **Electrical Characteristics – P Channel** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μA	$V_{DS} = -24V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1	-2.2	-2.6	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	D	_	0.5	0.9	Ω	$V_{GS} = -10V$ , $I_D = -0.42A$
Static Dialii-Source Off-Resistance	R <sub>DS(ON)</sub>	_	0.78	1.7	Ω	$V_{GS} = -4.5V, I_D = -0.2A$
Diode Forward Voltage	V <sub>SD</sub>	_	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -0.23A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C <sub>iss</sub>	_	19	_	pF	
Output Capacitance	Coss	_	16	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	3	_	pF	] = 1.0WHZ
Gate Resistance	Rg	_	4.4	_	kΩ	$V_{DS} = V_{GS} = 0V$ , $f = 1.0MHz$
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	0.36	_	nC	
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	0.8	_	nC	$V_{DS} = -10V, I_{D} = -0.24A$
Gate-Source Charge	Q <sub>gs</sub>	_	0.1	_	nC	$V_{DS} = -10V, I_{D} = -0.24A$
Gate-Drain Charge	$Q_gd$	_	0.1	_	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.3	_	ns	
Turn-On Rise Time	t <sub>R</sub>	_	2.3	_	ns	$V_{GS} = -10V, V_{DD} = -15V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	406	_	ns	$I_D = -0.5A, R_G = 1\Omega$
Turn-Off Fall Time	t <sub>F</sub>	_	237	_	ns	

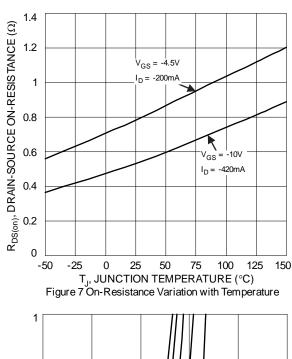
Notes:

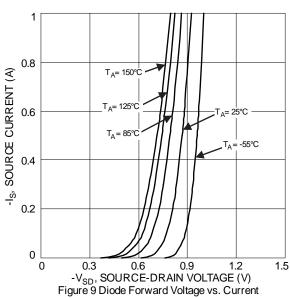
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
  Device mounted on FR-4 substrate PC board, 2oz copper, with 1in square copper plate.
  Short duration pulse test used to minimize self-heating effect.
  Guaranteed by design. Not subject to product testing.

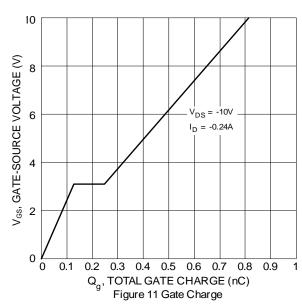












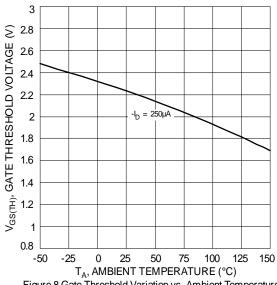
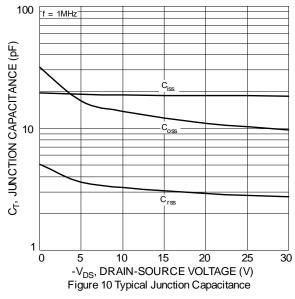
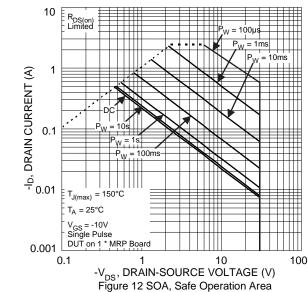
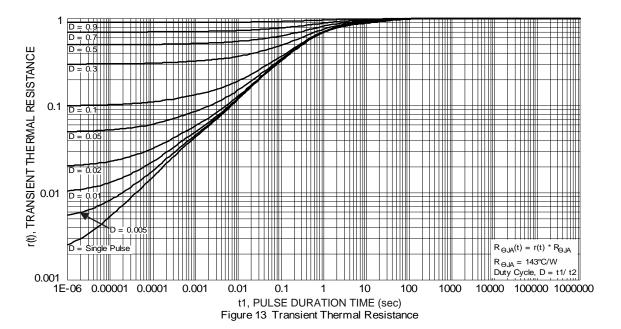


Figure 8 Gate Threshold Variation vs. Ambient Temperature





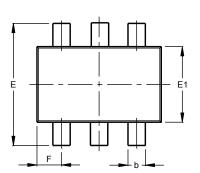


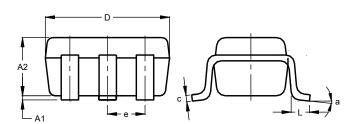




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.





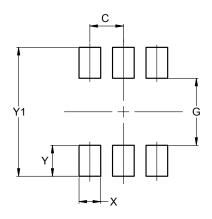
SOT363							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.10	0.30	0.25				
C	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	e 0.650 BSC						
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All Dimensions in mm							

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### **SOT363**

**SOT363** 



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.420
Υ	0.600
Y1	2.500



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